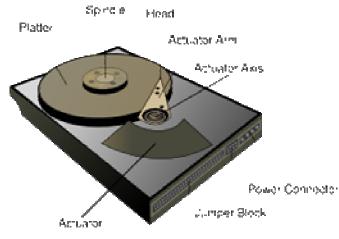


Magnetic Head Dicing Process



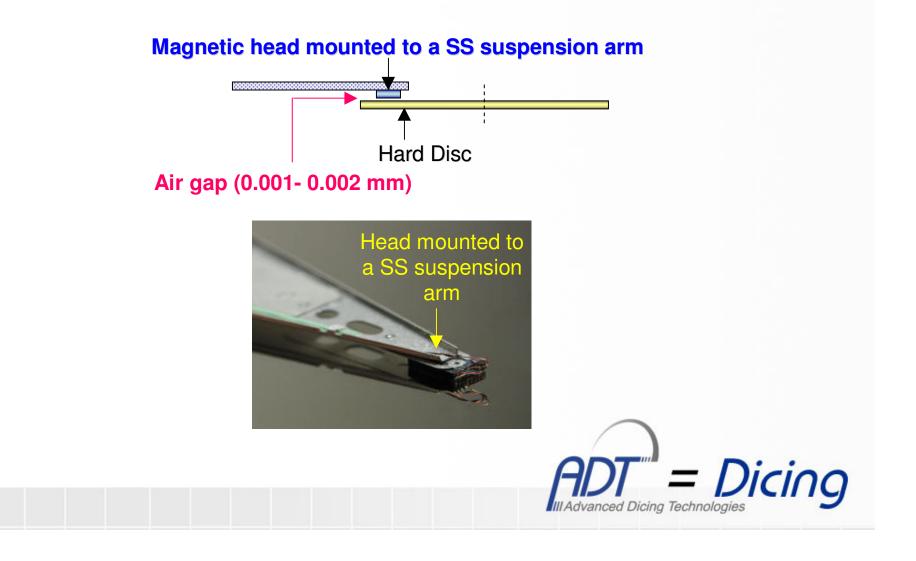
IDE Connector

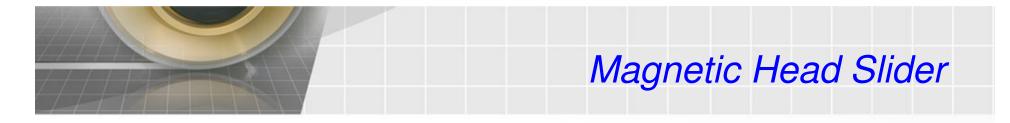






Basic function of head = reading information on the hard disc





Physical Properties of Al203-TiC :ColorDensity (g/Cm3)Black4.22100

Base material - Alumina + Titanium Carbide

Material to dice:

AL Titanium Carbide [ALTEC]

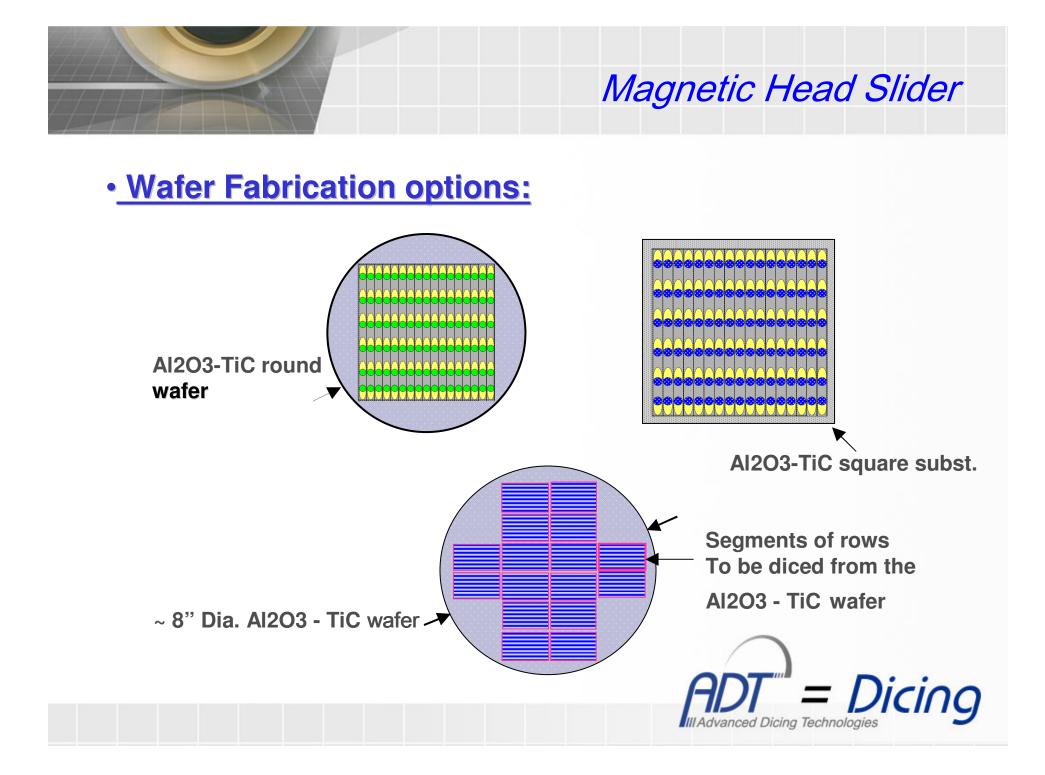
Sliders are composed of Al2O3 - TiC composite with a thin 10 - 20nm diamond like carbon protective overcoat

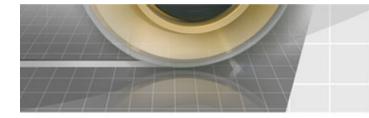


General Manufacturing process flow:

- Wafer Fabrication
- Wafer Mounting
- External shaping / dicing for reference
- Second wafer mounting [On some applications]
- Row Slicing
- Lapping the rows in reference to the coil
- Aligning and stack mounting of rows
- Head Parting
- Related to the dicing process

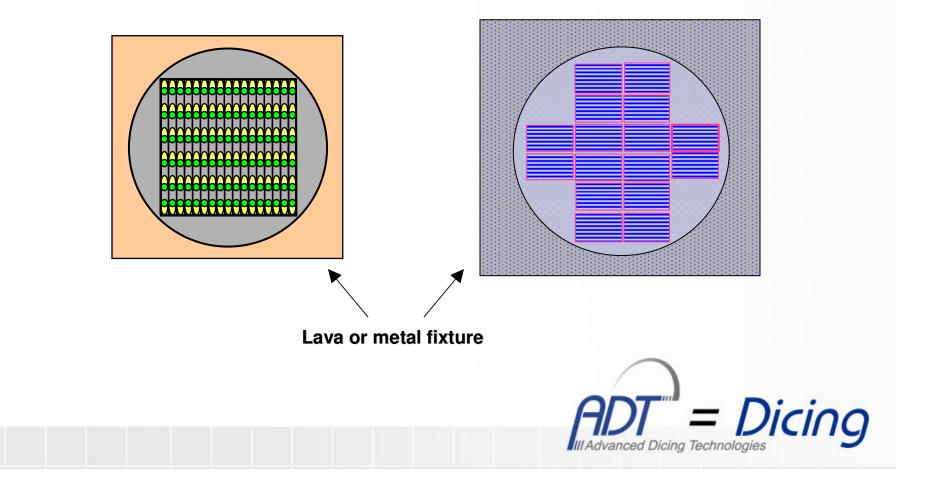






Wafer / substrate Mounting

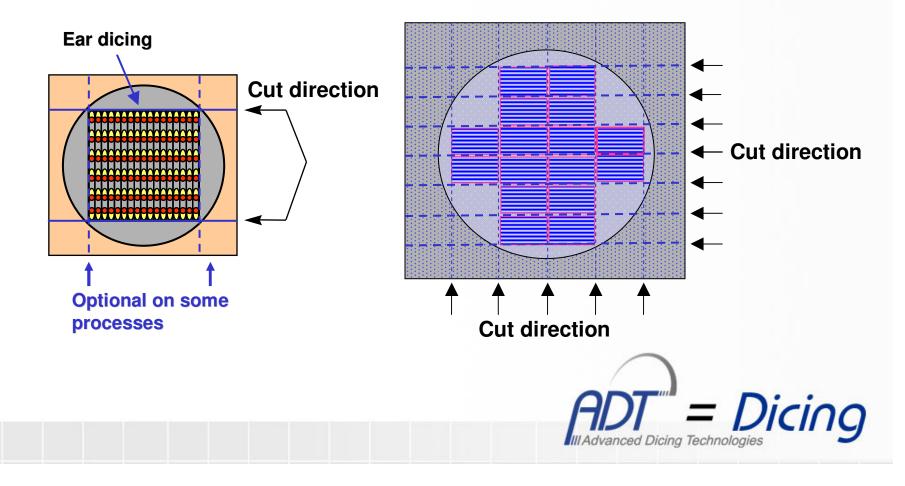
[Gluing or mechanical mounting]

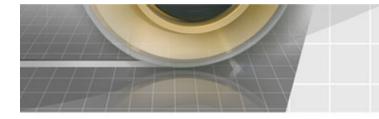


External shaping / Dicing :

Blade - Depending on the process requirements:

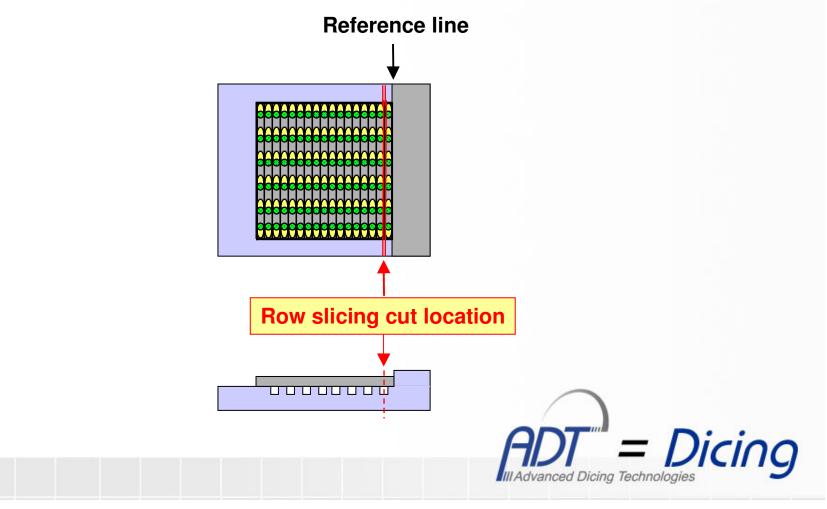
- Nickel or metal sintered x 4-8 & 10mic. Diamond grit
- On some square substrates this step is part of the next row slicing process





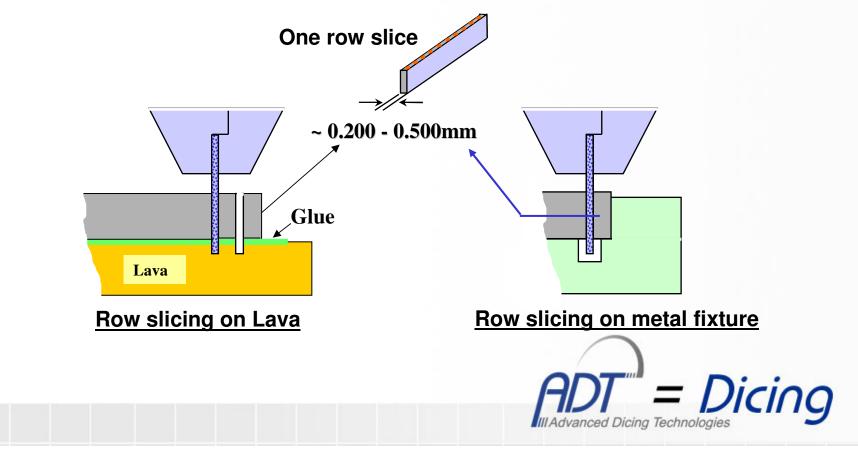
<u>2nd wafer mounting [On some application]</u>

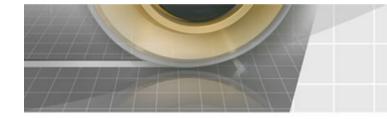
[Glue or Vacuum to metal fixture]



Row Slicing:

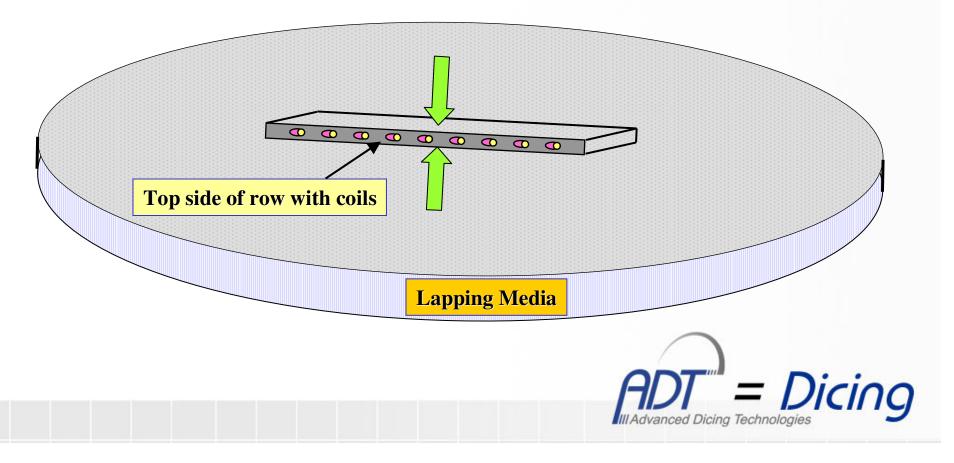
- Blade : Nickel electroformed x 0.100 0.150mm Thickness x 4- 8, 10 or 17mic. Grit
- Cut perpendicularity ~ 0.002 0.005mm depending on wafer thickness
- -Cut straightness [Skew] ~ 0.002 0.005mm depending on cut length
- -Chipping ~ 0.004 0.008mm depending on the application (Usually not an issue)



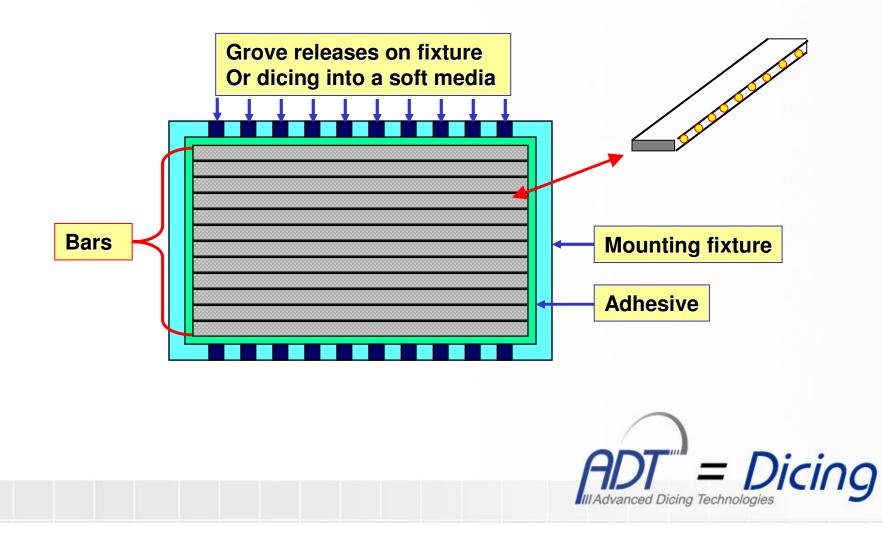


Lapping the rows in reference to the coil geometry:

Lapping the row sides for straightness & electrical properties



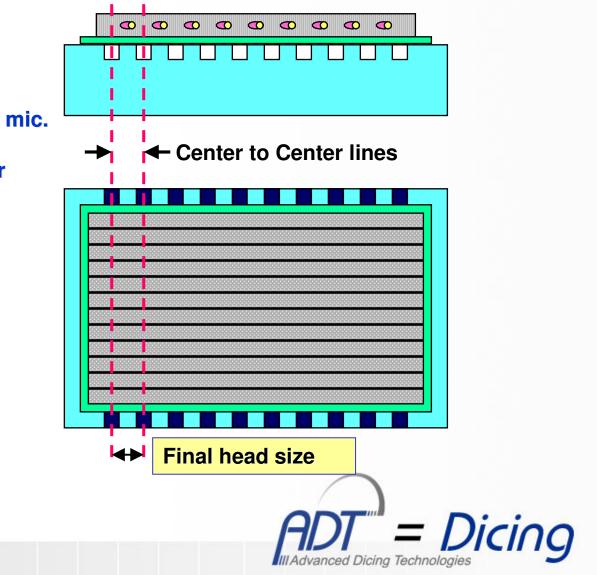
• <u>Aligning and stack mounting of rows:</u> [A delicate & accurate process]



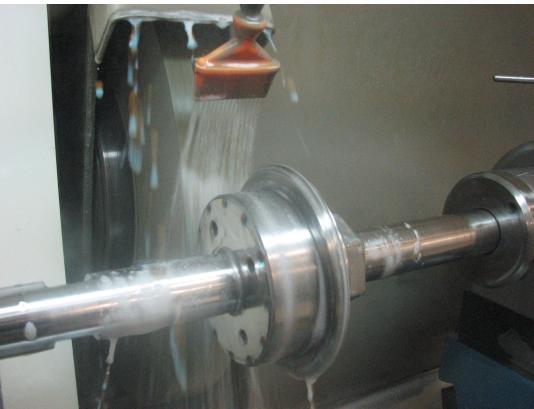


Head Parting:-

Blade being used: Nickel binder x 3- 6mic. Or 4-8 mic. x ~ 0.060 - 0.100mm thick [On some application a thicker blade is used]



Magnetic Head Slider **Important process parameters:** Side view Blade mounting and O.D. grinding **Grinding wheel rotation** Sil. Car. Grinding Wheel Flange Blade Work piece rotation **Arbor Top view** Dicing Advanced Dicing Technologies



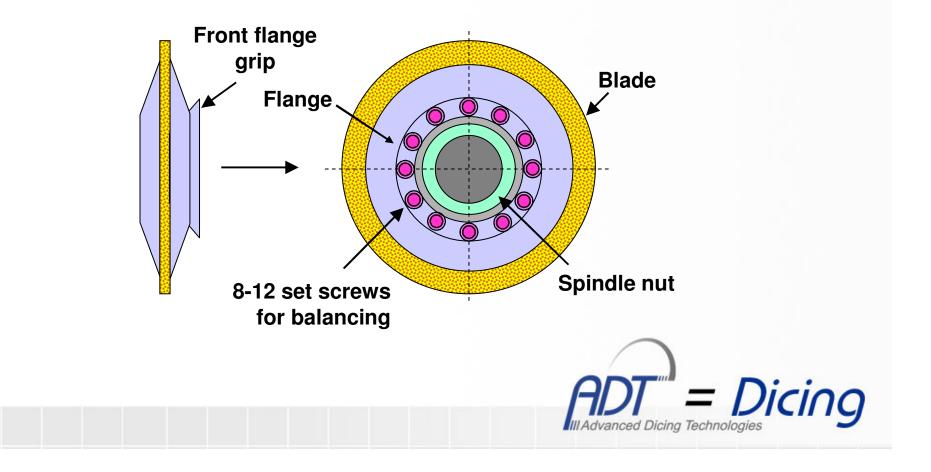


Flange set

Arbor



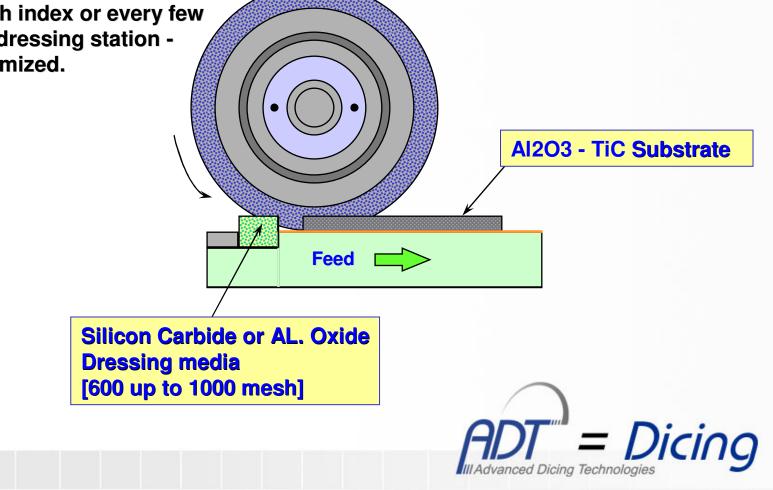
 Blade Dynamically balancing: common spec - < 0.001cm / sec



Cont.

On Line dressing

Blade is passing the dressing media each index or every few cuts on a dressing station To be optimized.



Cont.

Blade testing for spec :

- Blade must be functionally tested on Al2O3 - TiC substrate after the O.D. grinding process and prior to starting production

Blade Coolant:-

- Special additive to the cooling system must be used to lower the surface tension of the coolant and to better lubricate the blade during the dicing.
- Use lower pressure with high coolant volume, Important to eliminate any blade deflection.





Cont.

Proper mounting:-

- Eliminate any movement of bars [Skew and blade Walk]
- Optimize the glue type to minimize blade overloading

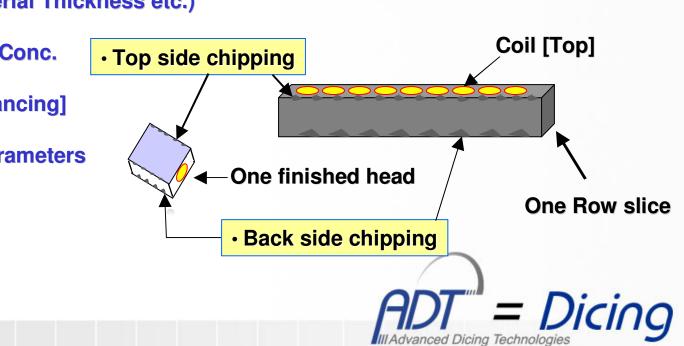


Quality criteria's for the row slicing & the parting:-

<u>General remark:</u> The quality criteria's spec depends on the customer application. All spec criteria's are in the microns range and do vary between customers

Factors effecting TSC & BSC:

- Substrate type (Material Thickness etc.)
- Blade matrix
- Diamond grit size & Conc.
- Coolant
- Blade vibration [balancing]
- Mounting
- Optimized dicing parameters

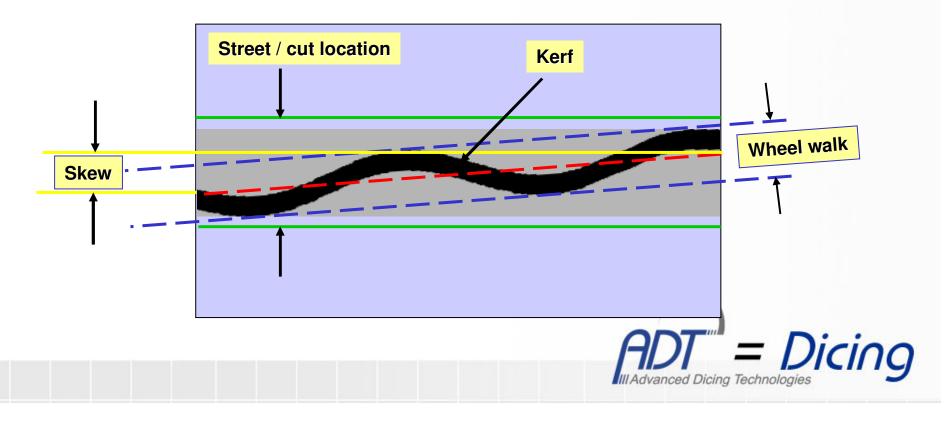


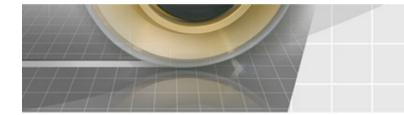
Magnetic Head Slider Cut perpendicularity: Factors effecting cut perpendicularity: - Blade matrix [Loading] - Blade exposure - Flange condition - Coolant type and pressure - Mounting 90° - Optimized dicing parameters Measured opticallyin microns = Dicing

Advanced Dicing Technologies

Wheel walk & Skew:

- Wheel walk is mainly a factor of the blade stiffness, blade exposure, wafer material [Loading] and the accuracy of the dicing saw
- Skew is mainly a factor of the blade matrix, part mounting / part movement during the dicing, wafer material [loading], accuracy of the saw [alignment] and accuracy of the wafer streets.

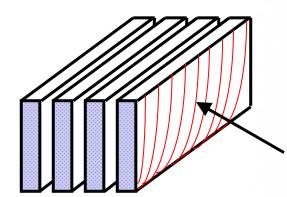




Surface finish on the kerf wall:

Factors that are effecting the surface finish:

- Blade binder & diamond grit size
- Wafer material
- Saw accuracy
- Blade exposure
- Spindle speed & feed rate
- Coolant type
- Blade vibrations dynamically balancing
- Mounting



Surface finish Measured in Angstroms



Picing

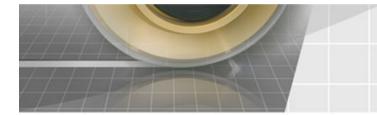
ADT typical recommended blades for Dicing magnetic head applications:-

Row slicing:

- Nickel Electroformed 4-8, 10 & 17mic. Grit Thickness of 0.090mm & over
- Parting:
- Nickel Electroformed 3-6, 4-8mic. Grit Thickness of 0.060mm & over

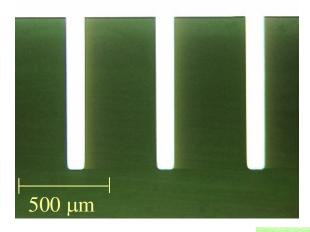
All blades are available in 2.0" [50mm] up to 4.30" [109.22mm] Diameters. Special diameters can be made.

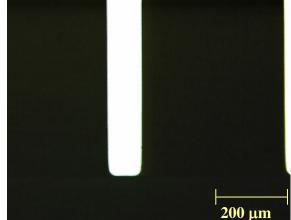
Other blade matrixes or blade parameters can be tailor made and optimized for special application requirements.



Typical qualification tests for the Row Slice process: Blade P/N - 04776-7301-038-ALO Blade thickness – 0.092mm

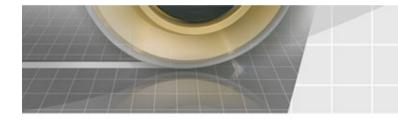
500 µm



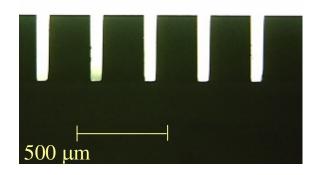


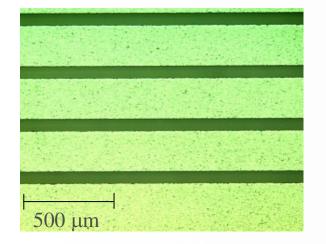
- Nice edge / min radius
- Kerf < 0.097mm
- Min chipping





Typical qualification tests for the Parting process: 4B777-ENGN-135 Blade thickness – 0.062mm





- Nice edge / min radius
- Kerf ~ 0.066mm
- Min chipping



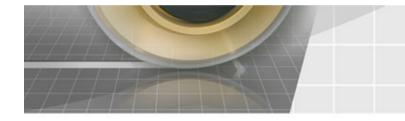
Blade P/N - ENGN-134 Wheel room test cut: (At the customer site)

Kerf – 0.064mm Right perpendicularity – 0.001mm Left perpendicularity – 0.002mm Right radius – 0.008mic. Left radius – 0.007mic.

Row part test after conditioning: (At the customer site)

Kerf – 0.065mm Right perpendicularity – 0.002mm Left perpendicularity – 0.001mm Right radius – 0.008mm Left radius – 0.007mm





Blade parameters to be optimized:

- Blade geometry Diameter, thickness
- Matrix hardness
- Diamond %
- Diamond size & type

